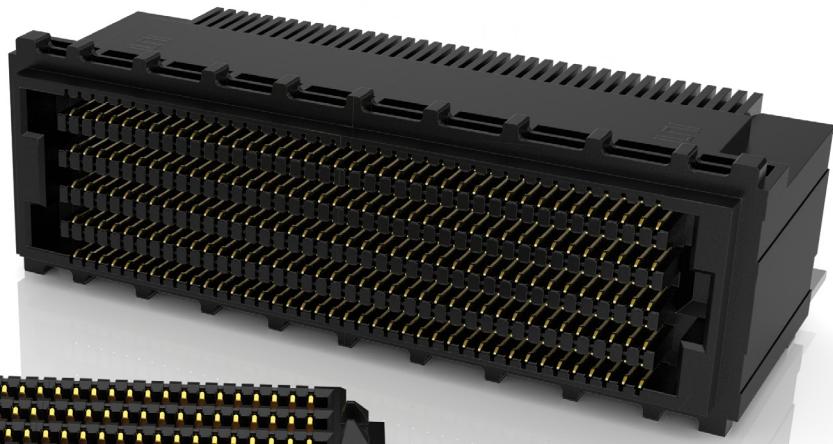


# SEARRAY<sup>TM</sup> 8 mm

## ULTRA HIGH-DENSITY, HIGH-SPEED OPEN-PIN-FIELD ARRAYS

(0.80 mm) .0315" PITCH

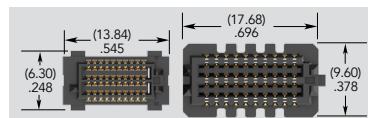
NRZ	PAM4
<b>28</b>	<b>56</b>
Gbps	Gbps



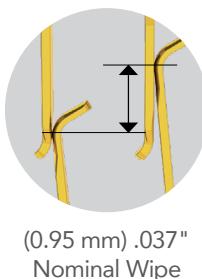
**EDGE RATE<sup>®</sup>**  
CONTACT

### FEATURES & BENEFITS

- 0.80 mm (.0315") pitch grid
  - 50% board space savings versus .050" (1.27 mm) pitch arrays
  - Performance up to 28 Gbps NRZ/56 Gbps PAM4
  - Rugged Edge Rate<sup>®</sup> contact system
  - Up to 500 I/Os
  - 7 mm and 10 mm stack heights
  - Solder charge terminations for ease of processing
  - Lower insertion/withdrawal forces
  - Severe Environment Testing qualified (SEAM8/SEAF8); aligns with MIL-DTL-55302.
- Visit [samtec.com/set](http://samtec.com/set)

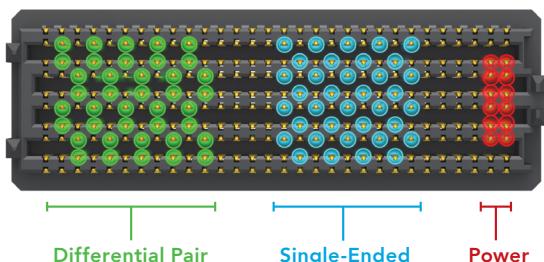


0.80 mm pitch vs. 1.27 mm pitch  
(60 pins shown)



(0.95 mm) .037"  
Nominal Wipe

### MAXIMUM GROUNDING & ROUTING FLEXIBILITY



### KEY SPECIFICATIONS (SEAF8/SEAM8)

SERIES	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
SEAM8					1.3 A per pin (10 adjacent pins powered)	220 VAC/311 VDC	
SEAF8	Black LCP	Copper Alloy	Au or Sn over 50 $\mu$ " (1.27 $\mu$ m) Ni	-55 °C to +125 °C			Yes
SEAF8-RA					1.1 A per pin (10 adjacent pins powered)	240 VAC/339 VDC	

(0.80 mm) .0315" PITCH • ULTRA HIGH-DENSITY ARRAYS

SERIES	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OPTION	"X"R
SEAM8 Terminal	-10, -20, -30, -40, -50	-S02.0 = 2 mm Body Height (SEAM8 only)	-L = 10 $\mu$ " (0.25 $\mu$ m) Gold on contact area, Matte Tin on solder tail	-04 -06 -08 -10	-3 = Lead-Free Solder Crimp	-GP = Guide Post (-S02.0 lead style only) (Mates with SEAF8-RA-GP)	Tape & Reel is standard. Leave blank for Tape & Reel.
SEAF8 Socket	-S05.0 = 5 mm Body Height (SEAM8 only)	-05.0 = 5 mm Body Height (SEAF8 only)				-FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)	
SEAM8	Board Mates: SEAF8	Cable Mates: ESCA	Standoffs: JSO				

**SEAM8**

Board Mates: SEAF8

Cable Mates: ESCA

Standoffs: JSO

**ALSO AVAILABLE**  
Contact Samtec

Other platings  
Tin/Lead solder crimps

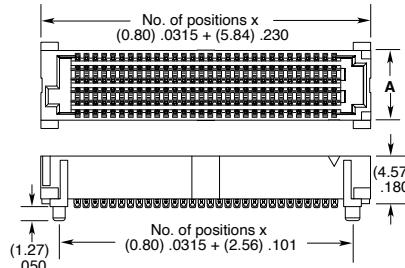
View complete specifications at: [samtec.com?SEAM8](http://samtec.com?SEAM8)

MATED HEIGHTS*		
SEAF8 LEAD STYLE	SEAM8 LEAD STYLE	
-S02.0	-S02.0	-S05.0
-05.0	(7.00) .276	(10.00) .394

\*Processing conditions will affect mated height.

**Notes:**  
Polyimide Pick & Place Pad  
standard without specifying -K.

Severe Environment Testing  
qualified; aligns with MIL-DTL-55302.  
Visit [samtec.com/set](http://samtec.com/set)



View complete specifications at: [samtec.com?SEAF8](http://samtec.com?SEAF8)

SEAF8	NO. PINS PER ROW	1	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	RA	OPTION	"X"R
SEAF8-RA (Right-angle)	-20, -30, -40, -50		-S = 30 $\mu$ " (0.76 $\mu$ m) Gold on contact area, Matte Tin on solder tail	-04 (-50 positions only) -08 -10	-2 = Lead-Free Solder Crimp	-GP = Guide Post Holes	Tape & Reel is standard. Leave blank for Tape & Reel.	
Board Mates: SEAM8	Cable Mates: ESCA	Standoffs: JSO					-FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)	

**SEAF8-RA**

Board Mates: SEAM8

Cable Mates: ESCA

**Notes:**  
Some sizes, styles and options are non-standard, non-returnable

**ALSO AVAILABLE**  
Contact Samtec

Other platings  
Tin/Lead solder crimps

View complete specifications at: [samtec.com?SEAF8-RA](http://samtec.com?SEAF8-RA)